Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	68134	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:14
S2	56	S1 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44
S3	44	S2 and (semiconductor adj manufacturing)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:33
S4	13	S3 and (integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 12:07
S5	9	S4 and model	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:46
S6	0	S5 and (fault adj detection adj model)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:15
S7	1	S3 and (fault adj detection adj model)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 12:13
S8	2	S2 and (fault adj detection adj model)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 14:51
S10	68134	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 14:51
S11	56	S10 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 14:51
S12	2	S11 and (fault adj detection adj model)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 14:52
S13	0	S12 and tuning	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 14:52

S14	14	S11 and tuning	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:20
S15	8	"6465263"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:15
S16	68134	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:33
S17	56	S16 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:33
S18	44	S17 and (semiconductor adj manufacturing)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:33
S19	2	S18 and (tuning adj process)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/03/01 15:34
S20	69638	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44
S21	61	S20 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44
S22	61	S20 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:50
S23	47	S22 and (semiconductor adj manufacturing)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44
S24	14	S23 and (integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44
S25	9	S24 and model	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:44

S26	4	("20020055801"|"20030042427"|"6055460"|"6465263").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 14:47
S27	2	S26 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/04 15:08
S28	69754	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/05 17:36
S29	62	S28 and (fault adj detection)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/05 17:36
S30	48	S29 and (semiconductor adj manufacturing)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/05 17:36
S31	15	S30 and (integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/05 17:36
S32	10	S31 and model	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/05 17:36
S33	70004	(ion adj implant$5) and semiconductor	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:14
S34	4	S33 and (fault adj detection adj model)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:19
S35	1	S34 and tuning	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:19
S36	1421	S33 and tuning	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:26
S37	14	S36 and (tool adj parameter)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:26

S38	2	S37 and fault	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:28
S39	60	S33 and (tuning adj process)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:28
S40	1	S39 and (tool adj parameter)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:28
S41	33	S39 and tool	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 12:28
S42	3	S41 and fault	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 13:42
S43	959	titanium adj electrode	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/05/18 13:49